

# Biotape

## Biometric fingerprint sensor for contactless payment cards

While contactless payments are rapidly gaining ground around the world, today's next big trend can already be seen on the horizon: on-card biometric authentication. Banks, government agencies and retailers are all looking for quicker and more secure identification and authentication solutions, and fingerprint recognition can deliver just this, eliminating the need for signatures and pin codes while allowing consumers to securely use contactless cards even for high value payments.

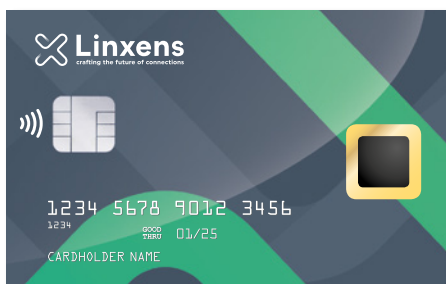
Linxens, a global leader in contact and contactless secured connectivity solutions, provides inlays and an interconnection technology that enable the easy integration of electronic components such as biometric sensors into ISO cards, allowing card manufacturers to leverage existing card manufacturing infrastructure and minimizing the need for investment in new machines. Linxens has partnered with leading biometric sensor manufacturer Fingerprint Cards to become the "one-stop-shop" for biometric card solutions. Linxens' streamlined supply chain is ready to deliver the critical components for high-volume production of biometric card systems for payments, access control and eGovernment applications, guaranteeing the highest quality and compatibility with all smartcard industry standards.

According to various studies, the use of Biometric payment cards are expected to grow significantly in the coming years, for several reasons:

- Secure alternative to PIN code-based payment cards
- No change on the infrastructure (POS, EMV terminals)
- Banks do not need back-end development

### Key Features

- Compatible with worldwide standard card integration process
- Thin tape and homogenous substrate for most efficient reading
- Black coverlay for great resistance against deterioration
- Plated Via to enable good referencing and ESD protection
- Delivered in standard smartcard 35mm reels
- Available for Anisotropic Conductive Film (ACF) connectivity
- Integrates in PRELAM® products employing wire-embedding technology or flexible PCB interlayer.



## MICROCONNECTORS



### Overview

#### Material

- Film base: Polyimide Cu clad
- Copper: 18µm
- Coverlay: Black solder mask

#### Thickness

- Total: 115 ± 20µm
- Plating Thickness
- Contact side:
  - Ni: 2.0 (-0.6 +1.0) µm
  - Au: 0.07 (-0.04 +0.04) µm
- Back side:
  - Ni: 5 (-2 +5) µm
  - Au: 0.3 (-0.1 +0.6) µm

#### Performance

- Standard corrosion resistance
- Hardness: >3H

#### Compliance Labels

- ISO 10373
- ISO 7810

#### Application Area

- Banking
- Access Control
- eGovernment

#### Options

- Edgelink® - Dual interface cards
- ACF (Anisotropic Conductive Film)
- Gold / Palladium